

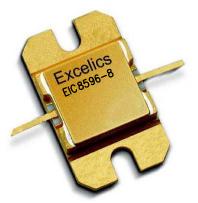
UPDATED 08/21/2007

8.50-9.60GHz 8-Watt Internally-Matched Power FET

FEATURES

- 8.50 –9.60GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +39.5 dBm Output Power at 1dB Compression
- 7.5 dB Power Gain at 1dB Compression
- 30% Power Added Efficiency
- -43 dBc IM3 at Po = 28.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}

ELECTRICAL CHARACTERISTICS (T_a = 25°C)



EIC8596-8

Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression f = 8.50-9.60GHz V _{DS} = 10 V, $I_{DSQ} \approx 2200$ mA	38.5	39.5		dBm
G _{1dB}		6.5	7.5		dB
∆G	Gain Flatnessf = 8.50-9.60GHz V_{DS} = 10 V, $I_{DSQ} \approx 2200$ mA			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V_{DS} = 10 V, $I_{DSQ} \approx 2200$ mAf = 8.50-9.60GHz		30		%
Id _{1dB}	Drain Current at 1dB Compression f = 8.50-9.60GHz		2200	2600	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 28.5 dBm S.C.L2 V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSSf = 9.60GHz	-40	-43		dBc
I _{DSS}	Saturated Drain Current V_{DS} = 3 V, V_{GS} = 0 V		3700	4300	mA
V _P	Pinch-off Voltage V_{DS} = 3 V, I_{DS} = 40 mA		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		2.5	3.5	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

2. S.C.L. = Single Carrier Level.

3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Gate-Source Voltage	-5V	-4V	
lgf	Forward Gate Current	96mA	28.8mA	
lgr	Reverse Gate Current	-19.2mA	-4.8mA	
Pin	Input Power	39.0dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Storage Temperature	-65C to +175C	-65C to +175C	
Pt	Total Power Dissipation	43W	43W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.



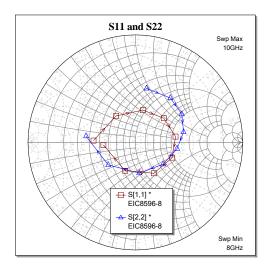
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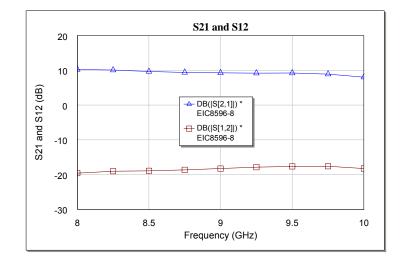
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PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50 Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} ≈ 2200mA

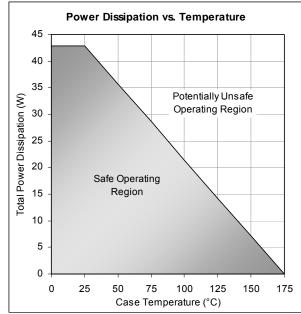




FREQ	S	S11		S21		S12		S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG	
8.00	0.390	177.400	3.255	-57.380	0.105	-114.220	0.514	78.300	
8.25	0.306	125.970	3.195	-88.570	0.112	-145.020	0.527	51.750	
8.50	0.309	77.020	3.052	-116.850	0.113	-173.180	0.507	31.300	
8.75	0.348	40.380	2.957	-144.300	0.117	161.600	0.459	12.160	
9.00	0.378	8.330	2.917	-170.590	0.122	135.400	0.393	-8.460	
9.25	0.371	-22.220	2.884	161.430	0.128	108.950	0.328	-38.080	
9.50	0.334	-59.000	2.897	132.320	0.131	81.650	0.287	-82.820	
9.75	0.280	-109.930	2.793	100.510	0.132	49.430	0.327	-140.430	
10.00	0.299	-175.540	2.528	66.690	0.122	16.320	0.462	172.730	
10.25	0.387	132.770	2.112	34.290	0.103	-16.260	0.614	140.720	
10.50	0.490	98.340	1.672	5.950	0.081	-45.080	0.713	117.810	

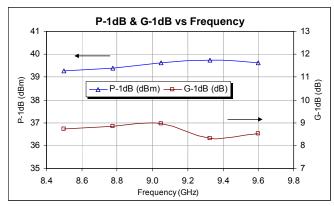
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Power De-rating Curve and IM3 Definition

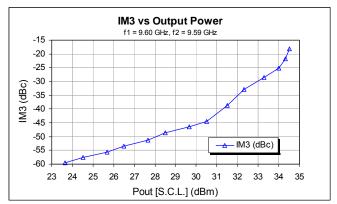


EIC8596-8

Typical Power Data (V_{DS} = 10 V, I_{DSQ} = 2200 mA)



Typical IM3 Data (V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSS)





UPDATED 08/21/2007



EIC8596-8

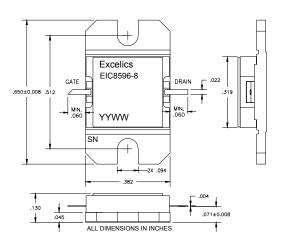
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UFDATED 06/21/2007

PACKAGES OUTLINE Dimensions in inches, Tolerance + .005 unless otherwise specified

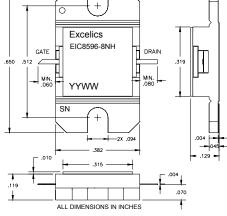
EIC8596-8 (Hermetic)





Caution! ESD sensitive device.

EIC8596-8NH (Non-Hermetic)





Caution! ESD sensitive device.

ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM_3 (min) ²
EIC8596-8	Hermetic	Industrial	8.50-9.60GHz	38.5	-40
EIC8596-8NH	Non-Hermetic	Industrial	8.50-9.60GHz	38.5	-40

Notes: 1. Contact factory for military and hi-rel grades.

2. Exact test conditions are specified in "Electrical Characteristics" table.

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